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Appl. No. : 10/055,568 Confirmation No. 6093
Applicant : Mou-Shiung Lin,
Jin-Yuan Lee,
Ching-Cheng Huang
Filed : January 22, 2002
TC/A.U. : 2813
Examiner : Mitchell, James M
Docket No. : MEGP0004USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

RESPONSE TO NON-FINAL OFFICE ACTION

Sir:

- 5 The Non-Final Office Action mailed Mar. 13, 2007 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

- 10 **Remarks/Arguments** begin on page 7 of this paper.